

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2626072

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>KU-FENG LIN</td> <td>11/18/2013</td> </tr> <tr> <td>HUNG-CHANG YU</td> <td>11/18/2013</td> </tr> <tr> <td>KAI-CHUN LIN</td> <td>11/18/2013</td> </tr> <tr> <td>YUE-DER CHIH</td> <td>11/18/2013</td> </tr> </tbody> </table>		Name	Execution Date	KU-FENG LIN	11/18/2013	HUNG-CHANG YU	11/18/2013	KAI-CHUN LIN	11/18/2013	YUE-DER CHIH	11/18/2013
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RECEIVING PARTY DATA											
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.										
Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED										
Internal Address:	INDUSTRIAL PARK,										
City:	HSINCHU										
State/Country:	TAIWAN										
Postal Code:	300										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14087782</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14087782						
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Application Number:	14087782										
CORRESPONDENCE DATA											
Fax Number:	(202)756-8087										
Phone:	202-756-8000										
Email:	IPDOCKETMWE@MWE.COM, BBEAVERS@MWE.COM										
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
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Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20001										
ATTORNEY DOCKET NUMBER:	050094-0161										
NAME OF SUBMITTER:	STEPHEN A. BECKER										

CH \$40.00 14087782

Signature:	/STEPHEN A. BECKER/
Date:	11/22/2013
Total Attachments: 2 source=assignment#page1.tif source=assignment#page2.tif	

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) _____
RESISTIVE MEMORY ARRAY AND FABRICATING METHOD THEREOF

The PATENT RIGHTS referred to in this agreement are:

(check one) a patent application for this invention, executed by the ASSIGNOR(S)
 concurrently with this assignment.

U.S. patent application Serial No. _____, filed _____

a U.S. patent application based on PCT International Application
 No. _____ filed on (date) _____ (U.S. patent application
 Serial No. _____, if known).

U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one) U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to
 claim the benefit of the filing date of any U.S. or foreign patent application
 for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.

(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,
TAIWAN 300, R.O.C.

The ASSIGNEE is:

(check one) An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable
 provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
 ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
 INVENTION TITLE: RESISTIVE MEMORY ARRAY AND FABRICATING METHOD THEREOF

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Ku-Feng LIN

Name of sole or first inventor

Ku-Feng Lin
Signature

2013.11.18
Date

Hung-Chang YU

Name of second inventor, if any

Hung-Chang Yu
Signature

2013.11.18
Date

Kai-Chun LIN

Name of third inventor, if any

kai-chun Lin
Signature

2013.11.18
Date

Yue-Der CHIH

Name of fourth inventor, if any

Yue-Der Chih
Signature

2013.11.18
Date